MiDAS DISPLAYS

MDCOG240128B6W-FPTLW	240 x 128	N/A	LCD Module
Specification			
Version: 1		Date: 02/01/2020	
Revision			
1	30/12/2019	First Issue	

Display Features		
Resolution	240 x 128	
Appearance	Black on White	
Logic Voltage	3.3V	
Interface	Parallel / SPI	
Font Set	N/A	
Display Mode	Transflective	
LC Type	FSTN	
Module Size	122.20 x 79.80 x 6.50mm	
Operating Temperature	-20°C ~ +70°C	
Construction	COG	**RoHS compliant**
		Box Quantity	Weight / Display
LED Backlight	White	---	---

* - For full design functionality, please use this specification in conjunction with the ST7586S specification. (Provided Separately)

Display Accessories	
Part Number	**Description**

Optional Variants	
Appearances	**Voltage**

General Specification

The Features is described as follow:

- Module dimension: 122.2 x 79.8 x 6.5 mm

- View area: 114.0 x 64.0 mm

- Active area: 107.98 x 57.58 mm

- Number of dots: 240 x 128

- Dot size: 0.43 x 0.43 mm

- Dot pitch: 0.45 x 0.45 mm

- LCD type: FSTN Positive Transflective

- Duty: 1/128Duty，1/12Bias

- View direction: 6 o'clock

- Backlight Type: LED White

- IC: ST7586S

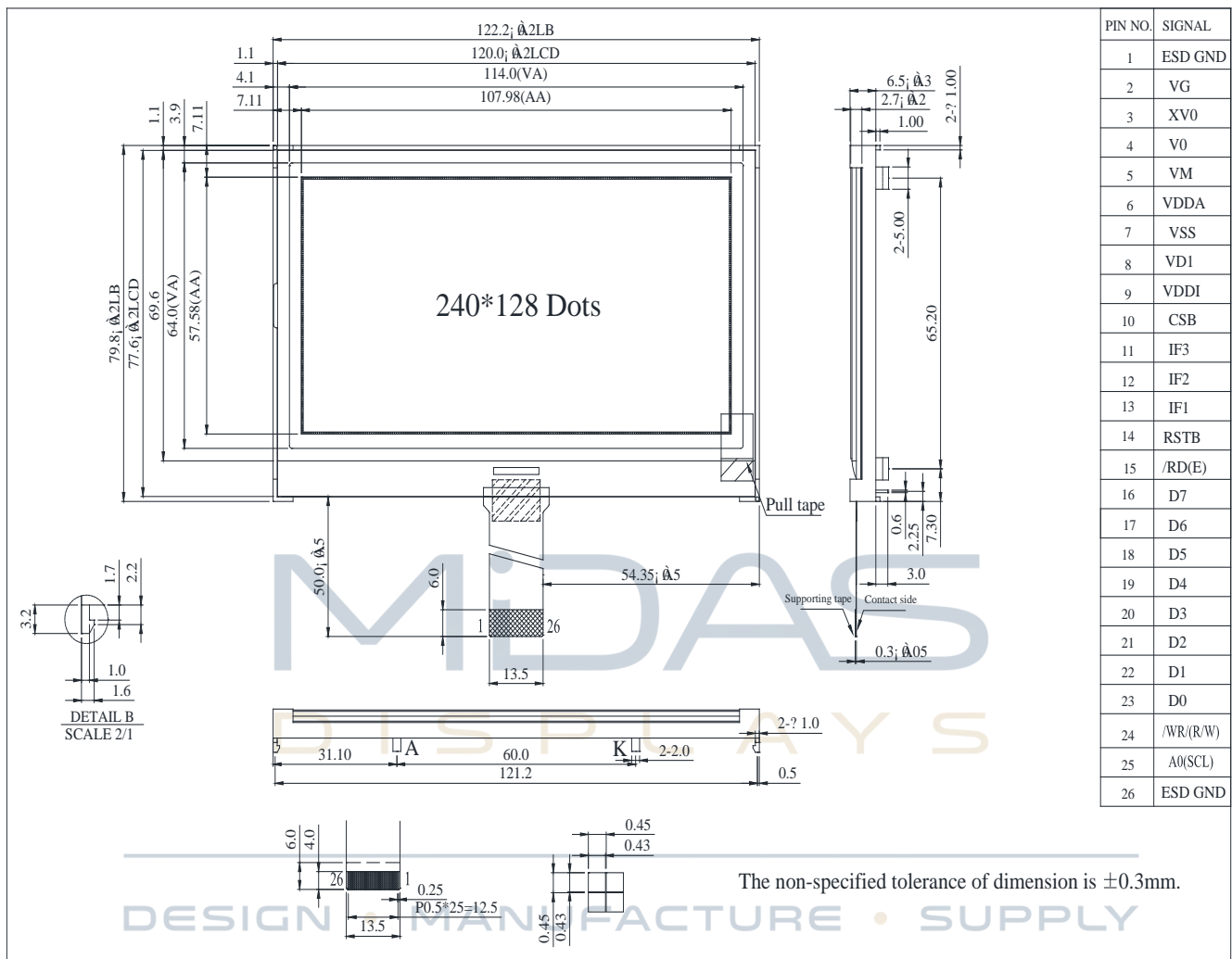DESIGN • MANUFACTURE • SUPPLY

Interface Pin Function

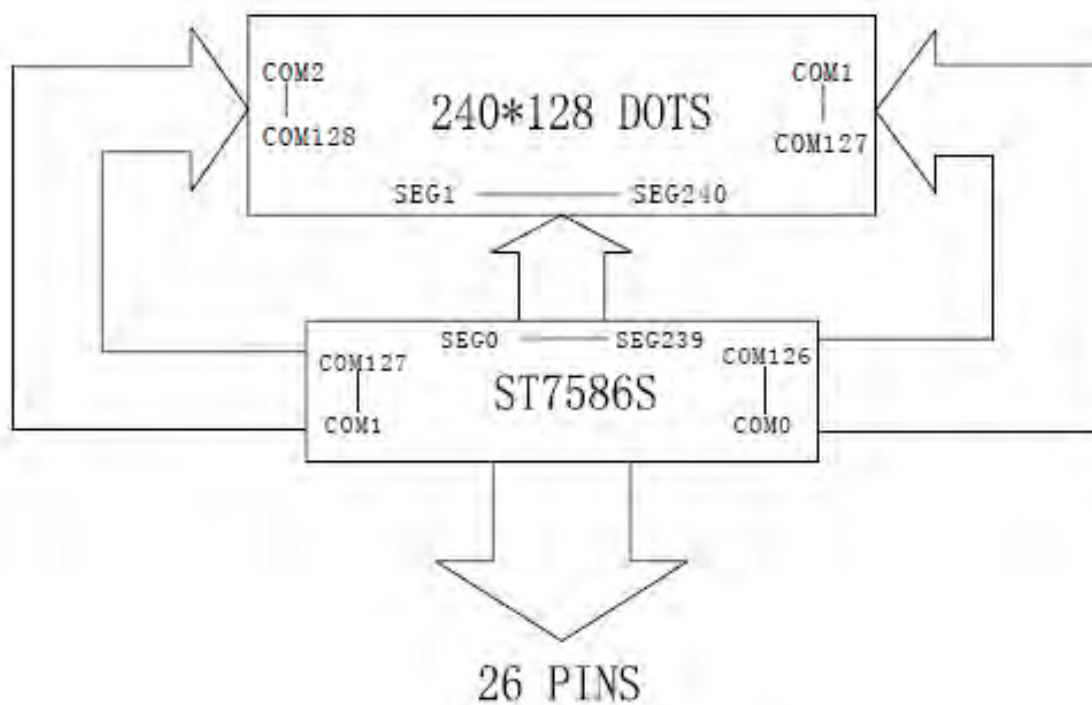| Pin No.	Symbol	Description
1	ESD GND	Electro-Static discharge
2	VG	VG is the power of SEG-drivers
3	XV0	Negative operating voltage of COM-drivers
4	V0	Positive operating voltage of COM-drivers
5	VM	VM is the non-select voltage level of COM-drivers
6	VDDA	Power supply
7	VSS	Ground
8	VD1	Digital power source selection
9	VDDI	VDD1 is the power of interface I/O circuit
10	CSB	Chip select input pin CSB="L": This chip is selected and the MPU interface is active CSB="H": This chip is not selected and the MPU interface is disabled (D[7:0] are high impedance)
11	IF3	These pins select interface operation mode <table><tr><th>IF3</th><th>IF2</th><th>IF1</th><th>MPU interface type</th></tr><tr><td>H</td><td>H</td><td>L</td><td>80 series 8-bit parallel</td></tr><tr><td>H</td><td>L</td><td>L</td><td>68 series 8-bit parallel</td></tr><tr><td>L</td><td>H</td><td>H</td><td>8-bit serial (4-Line)</td></tr><tr><td>L</td><td>H</td><td>L</td><td>9-bit serial (3-Line)</td></tr></table> Note: Refer to "Interface Selection" for detailed information
12	IF2	
13	IF1	
14	RSTB	Reset input pin. When RSTB is "L", internal initialization procedure is executed
15	/RD(E)	Read / Write execution control pin. (This pin is only used in parallelinterface) <table><tr><th>MPU Type</th><th>ERD</th><th>Description</th></tr><tr><td>6800-series</td><td>E</td><td>Read / Write control input pin. R/W = "H": When E is "H", data bus is in output status. R/W = "L": The data are latched at the falling edge of the E signal.</td></tr><tr><td>8080-series</td><td>/RD</td><td>Read enable input pin. When /RD is "L", data bus is in output status.</td></tr></table> This pin is not used in serial interfaces and should be connected to VDD1

16~23	D7~D0	The bi-directional data bus of the MPU interface. When CSB is "H", they are high impedance If using serial interface: D0 is the SDA signal in 4-Line & 3-Line interface D1 is the A0 signal in 4-Line interface
24	/WR/(R/W)	Read / Write execution control pin. (This pin is only used in parallel interface) | MPU Type	RWR	Description
6800-series	R/W	Read / Write control input pin R/W = "H" : read R/W = "L" : write
8080-series	/WR	Write enable clock input pin. The data are latched at the rising edge of the /WR signal. | This pin is not used in serial interfaces and should be connected to VDD1
25	A0(SCL)	The function of this pin is different in parallel and serial interface In parallel interface: A0 is register selection input A0 = "H": inputs on data bus are display data A0 = "L": inputs on data bus are command In serial interface: this pad will be used as SCL (serial-clock) input
26	ESD GND	Electro-Static discharge

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Contour Drawing & Block Diagram

PIN NO.	SIGNAL
1	ESD GND
2	VG
3	XV0
4	V0
5	VM
6	VDDA
7	VSS
8	VD1
9	VDDI
10	CSB
11	IF3
12	IF2
13	IF1
14	RSTB
15	/RD(E)
16	D7
17	D6
18	D5
19	D4
20	D3
21	D2
22	D1
23	D0
24	/WR/(R/W)
25	A0(SCL)
26	ESD GND

240*128 Dots

DETAIL B
SCALE 2/1

Pull tape

Supporting tape   Contact side

The non-specified tolerance of dimension is ±0.3mm.

Optical Characteristics

Item	Symbol	Condition	Min	Typ	Max	Unit
View Angle	θ	CR≧2	0	‒	30	ψ= 180°
	θ	CR≧2	0	‒	60	ψ= 0°
	θ	CR≧2	0	‒	45	ψ= 90°
	θ	CR≧2	0	‒	45	ψ= 270°
Contrast Ratio	CR	‒	‒	5	‒	‒
Response Time	T rise	‒	‒	200	300	ms
	T fall	‒	‒	250	350	ms

Definition of Operation Voltage (Vop)
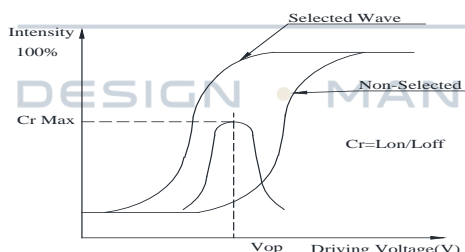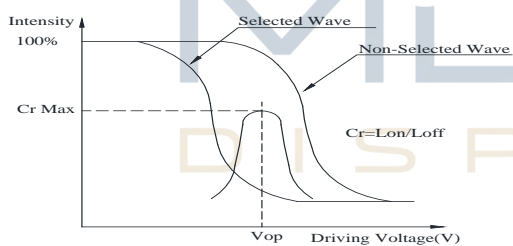
Definition of Response Time (Tr , Tf)

【 Positive type】

【 Negative type】
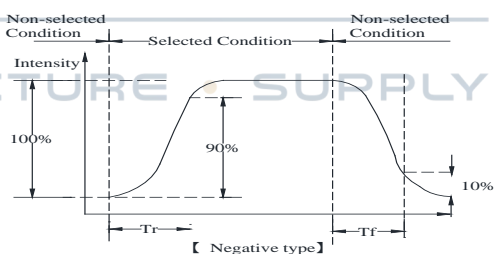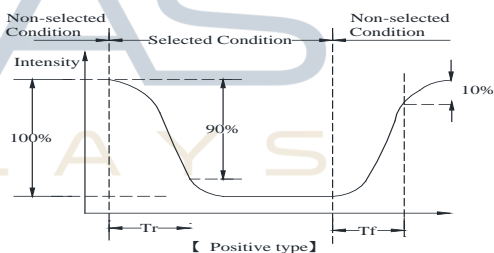
Conditions :

Operating Voltage : Vop   Viewing Angle(θ , φ) : 0° , 0°

Frame Frequency : 64 HZ Driving Waveform : 1/N duty , 1/a bias

Definition of viewing angle(CR≧2)
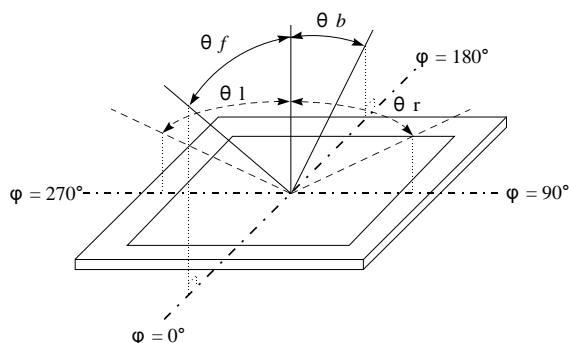
Absolute Maximum Ratings

Item	Symbol	Min	Typ	Max	Unit
Operating Temperature	T_{OP}	-20	—	+70	℃
Storage Temperature	T_{ST}	-30	—	+80	℃
Digital Power Supply Voltage	VDDI	-0.3	—	3.6	V
Analog Power supply voltage	VDDA	-0.3	—	3.6	V
LCD Power supply voltage	V0-XV0	-0.3	—	19	V
LCD Power supply voltage	VG	-0.3	—	5.5	V

Electrical Characteristics

Item	Symbol	Condition	Min	Typ	Max	Unit
Supply Voltage For Logic	V_{DD}-V_{SS}	—	3.0	3.3	3.6	V
Supply Voltage For LCM	VOP	Ta=-20℃	—	—	—	V
		Ta=25℃	14.8	15.0	15.2	V
		Ta=+70℃	—	—	—	V
Input High Volt.	V_{IH}	—	0.7V_{DD}	—	V_{DD}	V
Input Low Volt.	V_{IL}	—	Vss	—	0.3 V_{DD}	V
Output High Volt.	V_{OH}	—	0.8 V_{DD}	—	V_{DD}	V
Output Low Volt.	V_{OL}	—	Vss	—	0.2V_{DD}	V
Supply Current	I_{DD}	V_{DD}=3.3V	—	2.0	4.0	mA

Please kindly consider to design the Vop to be adjustable while programing the software to match LCD contrast tolerance.
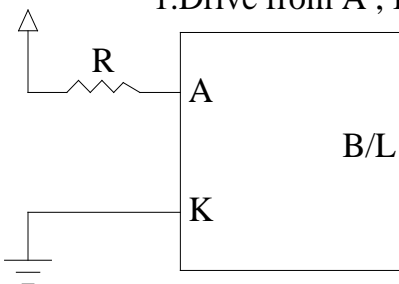
Backlight Information

Specification

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Supply Current	ILED	—	144	180	mA	V=3.5V
Supply Voltage	V	3.4	3.5	3.6	V	—
Reverse Voltage	VR	—	—	5	V	—
Color coordinate	X	0.244	0.264	0.284		ILED=144mA
	Y	0.264	0.284	0.304		
Luminance (Without LCD)	IV	750	940	—	CD/M²	ILED=144mA
LED Life Time (For Reference only)	—	—	50K	—	Hr.	ILED=144mA 25℃,50-60%RH, (Note 1)
Color	White					

Note: The LED of B/L is drive by current only, drive voltage is for reference only.
   drive voltage can make driving current under safety area (current between
   minimum and maximum).
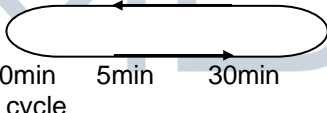Note 1:50K hours is only an estimate for reference.

LED B\L Drive Method
1.Drive from A , K

Reliability

Content of Reliability Test (Wide temperature, -20℃~70℃)

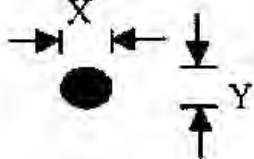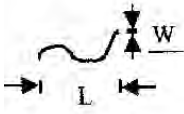| Environmental Test			
Test Item	**Content of Test**	**Test Condition**	**Note**
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80℃ 96hrs	2
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30℃ 96hrs	1,2
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70℃ 96hrs	───
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20℃ 96hrs	1
High Temperature/ Humidity storage	The module should be allowed to stand at 60℃,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60℃,90%RH 96hrs	1,2
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation -20℃ 25℃ 70℃ 30min 5min 30min 1 cycle	-20℃/70℃ 10 cycles	───
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude : 1.5mm Vibration Frequency : 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=±600V(contact), ±800v(air), RS=330Ω CS=150pF 10 times	───

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal

Temperature and humidity after remove from the test chamber.

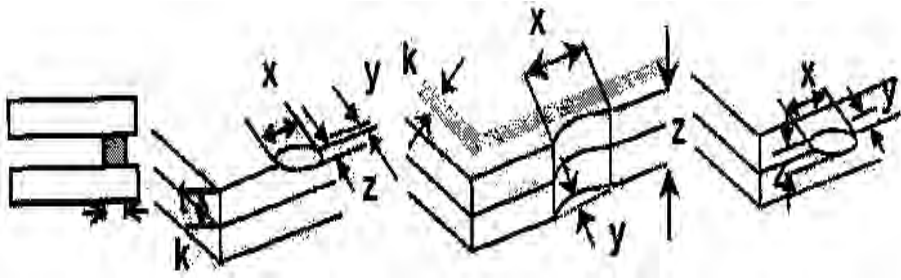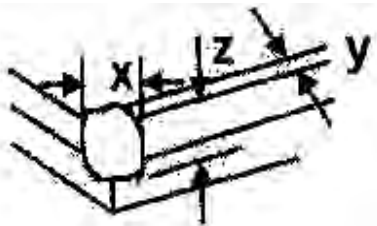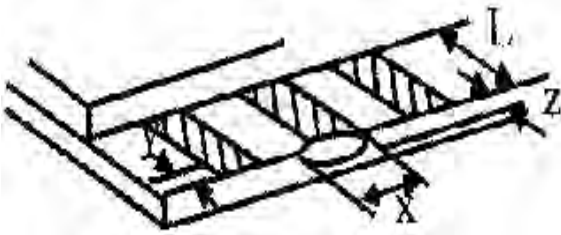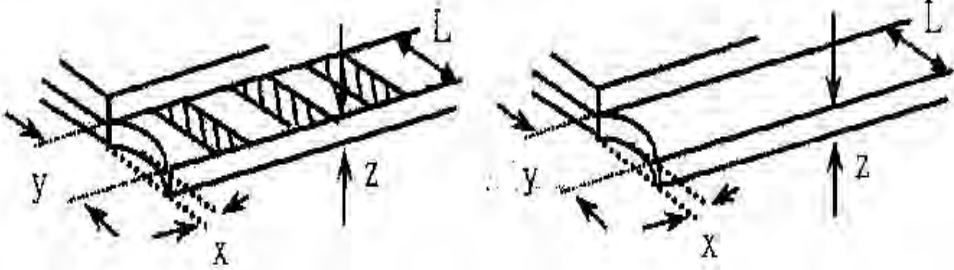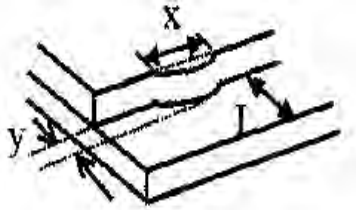**Note3: The packing have to including into the vibration testing.**
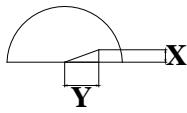
Inspection specification

NO	Item	Criterion	AQL
01	Electrical Testing	1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character , dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect.	0.65
02	Black or white spots on LCD (display only)	2.1 White and black spots on display $\leqq$ 0.25mm, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm	2.5

NO	Item	Criterion		AQL
03	LCD black spots, white spots, contamination (non-display)	3.1 Round type : As following drawing $\Phi=(x + y) / 2$	<table><tr><td>SIZE</td><td>Acceptable Q TY</td></tr><tr><td>$\Phi\leqq0.10$</td><td>Accept no dense</td></tr><tr><td>$0.10<\Phi\leqq0.20$</td><td>2</td></tr><tr><td>$0.20<\Phi\leqq0.25$</td><td>1</td></tr><tr><td>$0.25<\Phi$</td><td>0</td></tr></table>	2.5
		3.2 Line type : (As following drawing)	<table><tr><td>Length</td><td>Width</td><td>Acceptable Q TY</td></tr><tr><td>---</td><td>$W\leqq0.02$</td><td>Accept no dense</td></tr><tr><td>$L\leqq3.0$</td><td>$0.02<W\leqq0.03$</td><td rowspan="2">2</td></tr><tr><td>$L\leqq2.5$</td><td>$0.03<W\leqq0.05$</td></tr><tr><td>---</td><td>$0.05<W$</td><td>As round type</td></tr></table>	2.5
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction.	<table><tr><td>Size Φ</td><td>Acceptable Q TY</td></tr><tr><td>$\Phi\leqq0.20$</td><td>Accept no dense</td></tr><tr><td>$0.20<\Phi\leqq0.50$</td><td>3</td></tr><tr><td>$0.50<\Phi\leqq1.00$</td><td>2</td></tr><tr><td>$1.00<\Phi$</td><td>0</td></tr><tr><td>Total Q TY</td><td>3</td></tr></table>	2.5

NO	Item	Criterion	AQL
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination	
06	Chipped glass	Symbols Define: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length: 6.1 General glass chip : 6.1.1 Chip on panel surface and crack between panels: (see table below) ⊙If there are 2 or more chips, x is total length of each chip. 6.1.2 Corner crack: (see table below) ⊙If there are 2 or more chips, x is the total length of each chip.	2.5

6.1.1

z: Chip thickness	y: Chip width	x: Chip length
$Z \leqq 1/2t$	Not over viewing area	$x \leqq 1/8a$
$1/2t < z \leqq 2t$	Not exceed $1/3k$	$x \leqq 1/8a$

6.1.2

z: Chip thickness	y: Chip width	x: Chip length
$Z \leqq 1/2t$	Not over viewing area	$x \leqq 1/8a$
$1/2t < z \leqq 2t$	Not exceed $1/3k$	$x \leqq 1/8a$

NO	Item	Criterion	AQL
06	Glass crack	Symbols : x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 6.2 Protrusion over terminal : 6.2.1 Chip on electrode pad : 6.2.2 Non-conductive portion: 6.2.3 Substrate protuberance and internal crack. 	2.5

6.2.1 Chip on electrode pad :

y: Chip width	x: Chip length	z: Chip thickness
y ≦ 0.5mm	x ≦ 1/8a	$0 < z \leq t$

6.2.2 Non-conductive portion:

y: Chip width	x: Chip length	z: Chip thickness
y ≦ L	x ≦ 1/8a	$0 < z \leq t$

⊙If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.

⊙If the product will be heat sealed by the customer, the alignment mark not be damaged.

6.2.3 Substrate protuberance and internal crack.

y: width	x: length
y ≦ 1/3L	x ≦ a

NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
08	Backlight elements	8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong.	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination. 9.2 Bezel must comply with job specifications.	2.5 0.65
10	PCB、COB	10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB $X * Y <= 2mm2$	2.5 2.5 0.65 2.5 2.5 0.65 0.65 2.5 2.5
11	Soldering	11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB.	2.5 2.5 2.5 0.65

NO	Item	Criterion	AQL
12	General appearance	12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.	2.5
		12.2 No cracks on interface pin (OLB) of TCP.	0.65
		12.3 No contamination, solder residue or solder balls on product.	2.5
		12.4 The IC on the TCP may not be damaged, circuits.	2.5
		12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever.	2.5
		12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color.	2.5
		12.7 Sealant on top of the ITO circuit has not hardened.	2.5
		12.8 Pin type must match type in specification sheet.	0.65
		12.9 LCD pin loose or missing pins.	0.65
		12.10 Product packaging must the same as specified on packaging specification sheet.	0.65
		12.11 Product dimension and structure must conform to product specification sheet.	0.65
		12.12 Visual defect outside of VA is not considered to be rejection.	

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Precautions in use of LCD Modules

(1) Avoid applying excessive shocks to the module or making any alterations or modifications to it.

(2) Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.

(3) Don't disassemble the LCM.

(4) Don't operate it above the absolute maximum rating.

(5) Don't drop, bend or twist LCM.

(6) Soldering: only to the I/O terminals.

(7) Storage: please storage in anti-static electricity container and clean environment.

(8) Midas have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors,capacitors and other passive components will have different appearance and color caused by the different supplier.)

(9) Midas have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Midas have the right to modify the version.)

(10) To ensure the stability of the display screen, please apply screen saver after showing 30 mins of fixed display content.

(11) Please heat up a little the tape sticking on the components when removing it; otherwise the components might be damaged.

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12.Material List of Components for RoHs

1. Midas Displays hereby declares that all of or part of products (with the mark "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A：The Harmful Material List

Material	Cd	Pb	Hg	Cr6+	PBB	PBDE	DEHP	BBP	DBP	DIBP
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm
Above limited value is set up according to RoHS.										

2.Process for RoHS requirement：(only for RoHS inspection)

(1) Use the Sn/Ag/Cu soldering surface；the surface of Pb-free solder is rougher than we used before.

(2) Heat-resistance temp.：

Reflow：250℃,30 seconds Max.；

Connector soldering wave or hand soldering：320℃, 10 seconds max.

(3) Temp. curve of reflow, max. Temp.：235±5℃；

Recommended customer's soldering temp. of connector：280℃, 3 seconds.

Recommendable Storage

1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
2. Do not place the module near organics solvents or corrosive gases.
3. Do not crush, shake, or jolt the module.

Initial code

//For FSTN White

```
void initial()
{

    RES=1;
    delay(200);
    RES=0;
    delay(200);
    RES=1;
    delay(200);

    write_com(0xD7);        // Disable Auto Read
    write_dat(0x9F);
    write_com(0xE0);        // Enable OTP Read
    write_dat(0x00);
    delay(20);
    write_com(0xE3);        // OTP Up-Load
    delay(20);
    write_com(0xE1);        // OTP Control Out
    write_com(0x11);        // Sleep Out
    write_com(0x28);        // Display OFF
    delay(50);

    write_com(0xC0);        //----- Vop = 0X11Dh -----
    write_dat(0x1D);        //
    write_dat(0x01);        //

    write_com(0xC3);        // BIAS = 1/12 ----------
    write_dat(0x02);        //

    write_com(0xC4);        // Set Booster
    write_dat(0x07);

    write_com(0xD0);        // Enable Analog Circuit
    write_dat(0x1D);


    write_com(0xB5);        // N-Line = 0 ; Frame inversion
```

```
    write_dat(0x00);


    write_com(0x39);        //Display Mode : Monochrome mode(B/W Mode)


//--------------------   FSTN White Temperature Compensation
    write_com(0xF1);        // Frame Rate (Monochrome Mode)
    write_dat(0x06);        //
    write_dat(0x0B);        //
    write_dat(0x0D);
    write_dat(0x12);          //
//------------------   FSTN White Temperature Compensation
    write_com(0xF4);        //Temperature Gradient Compensation
    write_dat(0x7F);        //MT1 , MT0
    write_dat(0x22);        //MT3 , MT2
    write_dat(0x11);        //MT5 , MT4
    write_dat(0x02);        //MT7 , MT6
    write_dat(0x00);        //MT9 , MT8
    write_dat(0x32);        //MTB , MTA
    write_dat(0x82);        //MTD , MTC
    write_dat(0xB6);        //MTF , MTE
//-----------------


    write_com(0x3A);        // Enable DDRAM Interface
    write_dat(0x02);

    write_com(0x36);        // Scan Direction Setting/Display Control
    write_dat(0x00);



    write_com(0xB0);        // Duty Setting       --------------------
    write_dat(0x7F);        // 1/128Duty
//////////////////////
    write_com(0x20);        // Normal display


    write_com(0x37);        // Start Line
    write_dat(0x00);        //


    write_com(0xB1);        // First Output COM
    write_dat(0x00);        //
//////////////////////
```

```
write_com(0xB3);        //FOSC Divider
write_dat(0x00);        //

write_com(0x2A);        // Column Address Setting
write_dat(0x00);
write_dat(0x00);
write_dat(0x00);
write_dat(79);          //

write_com(0x2B);        // Row Address Setting
write_dat(0x00);
write_dat(0x00);
write_dat(0x00);
write_dat(127);         //


write_com(0x29);        // Display ON
}
```